



ASM International N.V.

ASM International Completes Acquisition of Genitech, Ltd.

Bilthoven, The Netherlands and Daejeon, South Korea, August 5, 2004 – ASM International N.V. (NASDAQ: ASMI and Euronext Amsterdam: ASM) announced today that it has completed the acquisition of Genitech, Inc., a privately-held semiconductor equipment supplier based in South Korea, for US\$ 5.2 million in cash and US\$ 4 million in ASMI common shares. The number of shares issued at the closing was 247,638. The total value of the consideration remained unchanged, but the portion of the consideration paid in ASMI common shares decreased compared to our earlier announcement.

As indicated in the April 26th announcement of the terms of the pending acquisition, ASM will also pay up to US\$ 9.2 million in cash over the next five years, depending upon the achievement of performance targets.

In making the announcement, Arthur del Prado, President and CEO of ASMI stated, “Today we are delighted that, in completing our acquisition of Genitech, ASMI has taken the final step in the consolidation of our leading edge interconnect platform – 3G Interconnect -- and cleared the path toward commercialization of these truly ground-breaking technologies for copper metallization. Genitech’s Plasma Enhanced Atomic Layer Deposition (PEALD[™]), provides complementary solutions to ASMI’s own pioneering Atomic Layer Chemical Vapor Deposition (ALCVD[™]) technology, and Genitech’s Cu Superfill CVD[™] addresses the need for atomic control of copper deposition without PVD, which will be critical for smaller device geometries, 45nm and beyond. In addition, we believe ALD barriers and Cu Superfill CVD[™] offer the ideal surface preparation for recently-acquired NuTool ECMD[™] technology on our Aurora® low-k film. With ASMI’s global presence, we see great potential for this suite of proprietary technologies to further penetrate the copper interconnect market.



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About Genitech and ASM

Founded in 1996 by researchers formerly with the Electronics & Telecommunications Research Institute (ETRI), Genitech, Ltd. is an innovative, dynamic, and privately held company, located in Korea, developing and manufacturing next generation semiconductor processing equipment for thin film deposition and copper metallization. Genitech has developed thin film deposition tools for PEALD™ (Plasma Enhanced Atomic Layer Deposition) of dielectric or metallic films and for Cu Superfill CVD™ of copper films for next generation metallization and interconnections. For more information, visit Genitech's website at www.genitech.co.kr.

Genitech is a trademark of Genitech, Ltd.

ASM International N.V., headquartered in Bilthoven, the Netherlands, is a global company servicing one of the most important and demanding industries in the world. The company and its subsidiaries design and manufacture equipment and materials used to produce semiconductor devices, including production solutions for wafer processing (Front-end segment) and assembly and packaging (Back-end segment). The company possesses a strong technology base, state-of-the-art manufacturing facilities in the United States, Europe, Japan and Asia, a competent and qualified workforce and a highly trained, strategically distributed support network. ASM International's common stock trades on NASDAQ (symbol ASMI) and the Euronext Amsterdam Stock Exchange (symbol ASM). For more information, visit the ASM International website at www.asm.com.

ASM is a registered trademark of ASM International N.V.

Safe Harbor Statement under the U.S. Private Securities Litigation Reform Act of 1995: All matters discussed in this statement, except for any historical data, are forward-looking statements. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. These include, but are not limited to, economic conditions and trends in the semiconductor industry, currency fluctuations, the timing of significant orders, market acceptance of new products, competitive factors, litigation involving intellectual property, shareholder and other issues, commercial and economic disruption due to terrorist activity, armed conflict or political instability and other risks indicated in the Company's filings from time to time with the U.S. Securities and Exchange Authorities.

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